

Electromagnetic Simulation Software

Electrostatic Discharge (ESD) Simulation and Prediction for RF Devices

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Overview



- 1. Static Electricity and Electrostatic Discharge (ESD)
- 2. Electrostatic Discharge Testing
- 3. Prediction of ESD with XFdtd[®] Electromagnetic Simulation Software
- 4. Spark Discharge Modeling
- 5. Multiphysics ESD Analysis
- 6. Conclusions



Static Electricity



Causes:

- Contact / Triboelectric
- Pressure / Piezoelectric
- Temperature / Pyroelectric
- Charge / Electrostatic Induction

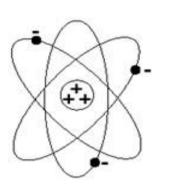




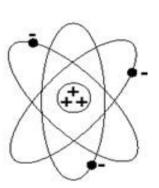
Triboelectric Charge



Triboelectric Charge

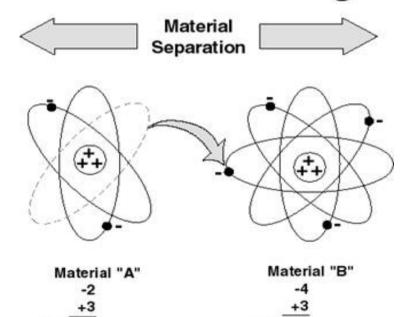


Material "A" -3 +3 Net = 0



Material "B" -3 +3 Net = 0

Triboelectric Charge



Source: [1]

Net = +1

REMC

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Net =

Triboelectric Charge



q = CV

- q Charge (Coulombs)
- C Capacitance (Farads)
- V Voltage (Volts)

$$E = \frac{1}{2}CV^{2}$$

E - Energy (joules)

Examples of Static Generation - Typical Voltage Levels		
Means of Generation	10-25% RH	65-90% RH
Walking Across Carpet	35,000V	1,500V
Walking Across Vinyl Tile	12,000V	250V
Worker at a Bench	6,000V	100V
Poly Bag Picked up from Bench	20,000V	1,200V
Chair with Urethane Foam	18,000V	1,500V

Source: [1]



Electrostatic Discharge





ESD Cost



"... in the electronics industry, losses associated with ESD are estimated at between a half billion and five billion dollars annually."

- In reality, total ESD cost is very difficult to determine.
- Facts:
 - Multiple Prototypes
 - Warranty Claims
 - Loss of Consumer Confidence

Reference: [2]





ESD Testing



Standards:

• ANSI/ESD, IEC, JEDEC, MIL, etc.

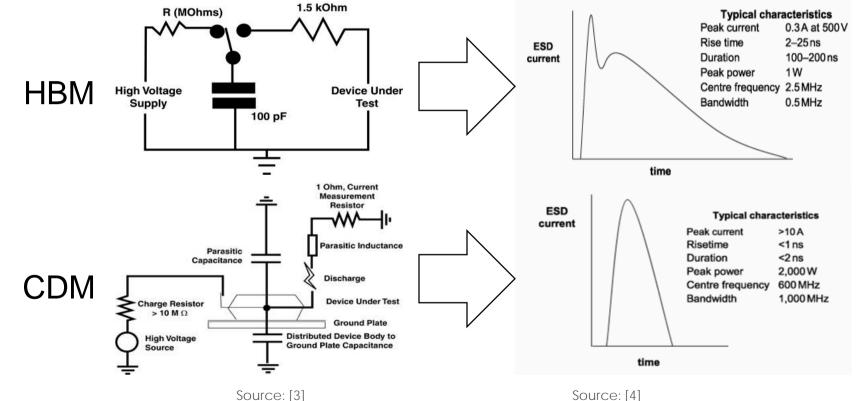
Test Models:

- Human Body Model (HBM)
- Charged Device Model (CDM)
- Machine Model (MM)
- etc.



HBM & CDM Models



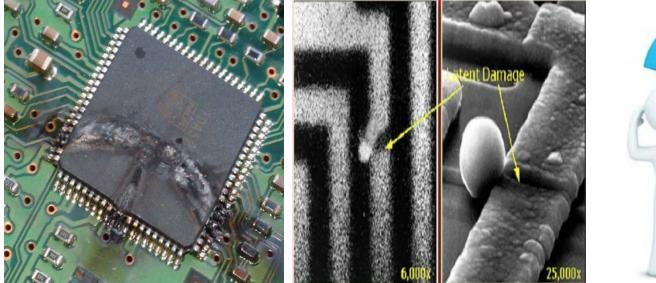


ESD Damage

MICROAPPS 2017 Nuremberg

Catastrophic

Latent

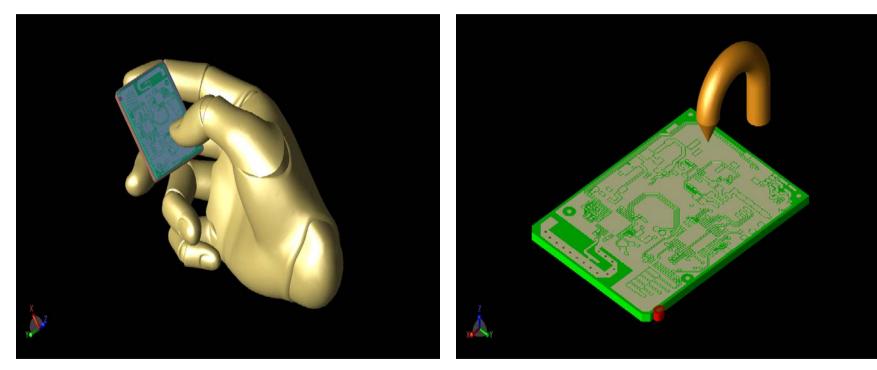


Upset



XFdtd Case Study



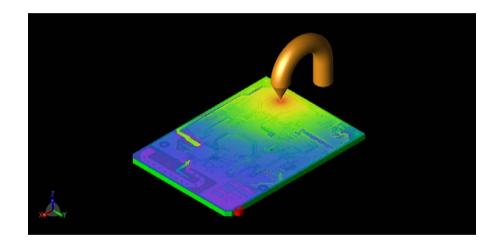




New XFdtd Functionality

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- ESD Waveforms
 - ➢ HBM, CDM, MM, etc.
- Material Parameter
 - Dielectric Strength
- Circuit Components
 - Rated Voltage/Current
- Result Sensor
 - Dielectric Breakdown

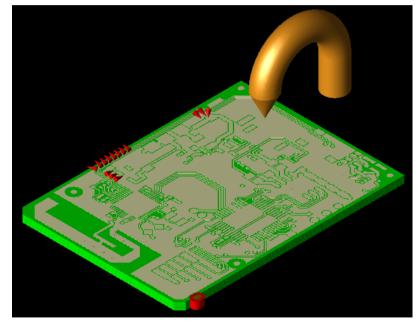




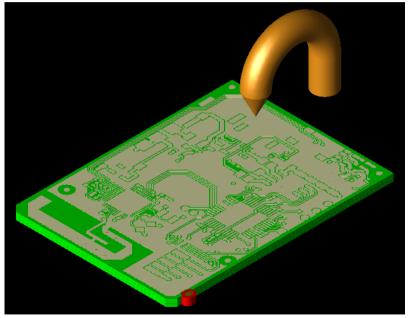
XFdtd ESD Design



Potential Dielectric Breakdown



After ESD Design Optimization



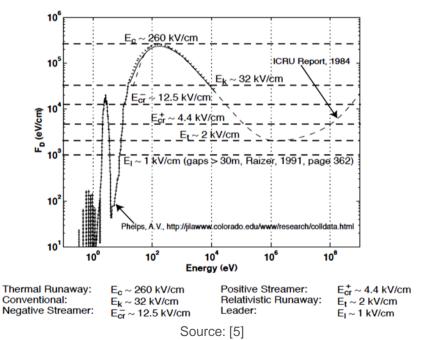


Spark Discharge



- Lorentz Force Law $\vec{F} = q(\vec{E} + \vec{v} \times \vec{B})$
- Plasma Modeling
 Fluid or Kinetic
- $f(\vec{v}, \vec{r}, t)$ Electron Energy Distribution Function
- Boltzmann Equation $\frac{\partial f}{\partial t} + \vec{v} \cdot \frac{\partial f}{\partial \vec{r}} + \frac{\vec{F}}{m} \cdot \frac{\partial f}{\partial \vec{v}} = \left(\frac{\partial f}{\partial t}\right)$

Dynamic Friction Force of Air



Boltzmann Solutions



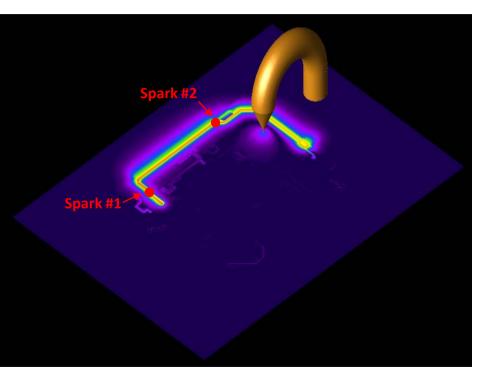




Multiphysics ESD Analysis



- Model subsequent spark discharges and overcurrents
- Pinpoint device/pin failure with transient FDTD/Circuit co-simulation
- Predict thermal damage utilizing FDTD/Thermal co-simulation





Conclusions



- ESD simulation does not replace hardware testing.
- ESD simulation does allow engineers to predict potential ESD problems and optimize ESD protection in the design phase.
 - Reduce number of hardware prototypes
 - Reduce product development cost
 - Reduce time to market
 - Improve product reliability



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